

PCN Number:	20171214002		PCN Date:	Dec 18, 2017	
Title:	Qualification of Aizu and JCAP as additional Fab, Bump and Assembly/Test site options for select devices in the CMOS9T process				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Mar 18, 2018		Estimated Sample Availability:	Date provided at sample request.	
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the addition of Aizu and JCAP as additional Fab, Bump and Assembly/Test site options for the selected devices listed in the "Product Affected" section.					
Group 1 Fab Site:					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
MAINEFAB	CMOS9T	200mm	AIZU	CMOS9T	200mm
Group 2 Fab & Assembly/Test Site:					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
MAINEFAB	CMOS9T	200mm	AIZU	CMOS9T	200mm
Current Bump/Assembly/Test Site			Additional Bump/Assembly/Test Site		
TIEM	Assembly Site Origin (22L) ASO: CU6		JCAP	Assembly Site Origin (22L) ASO: JCP	
Aizu and JCAP are already established Fab and Assembly/Test sites for select output voltage options of the LP5907 family of devices as was communicated in PCN 20131122000 on March 2, 2014. This PCN is to introduce additional output voltage options.					
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ. Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .		

Changes to product identification resulting from this PCN:

Fab Site:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland
AIZU	CU2	JPN	Aizuwakamatsu-shi

Assembly Site

TIEM-AT	Assembly Site Origin (22L)	ASO: CU6
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2d:
 MSL 2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected Group 1 (Adding Aizu Fab Site):

LP5907UVX-1.2/NOPB	LP5907UVX-3.0/NOPB	LP5907UVX-3.1/NOPB	LP5907UVX-4.5/NOPB
LP5907UVX-2.8/NOPB			

Product Affected Group 2 (Adding Aizu Fab and JCAP Bump, A/T Site):

LP5907UVE-1.2/NOPB	LP5907UVE-3.0/NOPB	LP5907UVE-4.5/NOPB	LP5907UVX-3.2/NOPB
LP5907UVE-1.8/NOPB	LP5907UVE-3.1/NOPB	LP5907UVX1.875-S	LP5907UVX-3.3/NOPB
LP5907UVE-2.7/NOPB	LP5907UVE-3.2/NOPB	LP5907UVX-2.7/NOPB	LP5907UVX37/NOPB
LP5907UVE-2.8/NOPB	LP5907UVE-3.3/NOPB		

Qualification Report

**CMOS9T 5V Process Transfer Maine to Aizu
LP5907UVX-3.3
Approved: June 27, 2013**

Product Attributes

Attributes		Qual Device: LP5907UVX-3.3		
Assembly Site	TIEM-MALACCA			
Package Family	YKE			
Flammability Rating	UL 94 V-0			
Wafer Fab Supplier	AIZU			
Wafer Process	CMOS9T			
Moisture Sensitivity Level	LEVEL1-260C			
		Qual Device: LP5907UVX-3.3		
Test Type	Conditions/Duration	# Lots	SS/Lot	Fails
**High Temp. Storage Bake	150C (1000 Hrs)	2	77	0
**T/C -65C/150C	-65C/+150C (500 Cyc)	3	77	0
**Unbiased HAST	130C/85%RH (96 Hrs)	3	77	0
Biased Temp. Humidity	85C/85%RH (1000 Hrs)	3	77	0
Early Life Failure Rate.	125C (48 hrs)	3	305	0
ESD CDM	+/- 250V	3	3	0
ESD HBM	+/- 1500V	3	3	0
High Temp Operating Life	125C (1000 Hrs)	3	77	0
Latchup @ 25C ,85 and 125C	(per JESD78)	3	6	0
**Units undergo pre-conditioning before stress - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1khrs, 140C/480hrs, 150C/300hrs, and 155C/240hrs - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1khrs, and 170C/420hrs - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700cyc and -65C/150C/500cyc				

Qualification Report

CMOS9T LP5907UVX2.85 Transfer to Aizu/JCAP

Approved: August 23, 2013

Product Attributes

Attributes		Qual Device: LP5907UVX2.85		
Assembly Site	JCAP			
Package Family	YKE			
Flammability Rating	UL 94 V-0			
Wafer Fab Supplier	AIZU			
Wafer Process	CMOS9T			
Moisture Sensitivity Level	LEVEL1-260C			
		Qual Device: LP5907UVX2.85		
Test Type	Conditions/Duration	# Lots	SS/Lot	Fails
**T/C -65C/150C	-65C/+150C (500 Cyc)	3	77	0
**BIASED HAST	130C/85%RH (96 Hrs)	3	77	0
**Units undergo pre-conditioning before stress - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700cyc and -65C/150C/500cyc				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com